

LPM 2010

11th International Symposium
on Laser Precision Microfabrication (LPM 2010)
June 7-10, 2010
in Stuttgart, Germany

co located with

LASYS

International trade fair for system
solutions in laser material processing

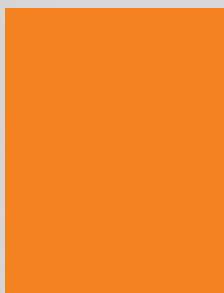
Interchange between research and industry

Miniaturization and high precision are rapidly becoming a requirement in many industrial processes and products. As result, there is greater interest in the use of laser micro-fabrication approaches to achieve these goals. The International Symposium on Laser Precision Microfabrication (LPM) is annually held to provide a forum for research and technology development in the area of **laser micro/nanofabrication**. The unique aspect of this symposium is the **interchange between fundamental research and industrial applications**.

LPM is held alternatively in Japan and in other host countries. To date, LPM has been successfully hosted in Omiya, Singapore, Osaka, Munich, Nara, Williamsburg,

Kyoto, Vienna, Quebec and Kobe. In 2010 it will be held in the International Congress Center on the new fair-grounds of Stuttgart, concurrently with International Trade Fair for System Solutions in Laser Materials Processing LASYS and Stuttgarter Lasertage SLT.

Stuttgart, well known as car capital is also the center of one of the most advanced regions in the field of manufacturing with lasers. Suppliers like Trumpf and pioneering users like Daimler and Bosch are located here and benefit from renowned research infrastructure.



Joint sessions

The 50th birthday of the LASER will be celebrated in a session co-organized by LASYS, SLT and LPM giving worldwide known laser pioneers the opportunity to look back to the origins and the enormous development since. Latest developments of **laser sources** and **industrial application success stories** will be presented in joint plenary sessions of both meetings.

Organizers

JLPS Japan Laser Processing Society
Landesmesse Stuttgart GmbH
Dausinger + Giesen GmbH Stuttgart

General Chair

Koji Sugioka (RIKEN, Japan)

Co-chairs

Friedrich Dausinger
(Dausinger+Giesen GmbH, Germany)
Hiroyuki Niino (AIST, Japan)
Alberto Pique (NRL, USA)
Kazuyoshi Itoh (Osaka University, Japan)
Seiji Katayama (Osaka University, Japan)
Arnold Gillner (Fraunhofer ILT, Germany)

LPM Topics

1. Fundamental aspects (Dynamic, modeling, simulation, etc.)
2. Process monitoring and control
3. Nanotechnology
4. Direct write process (MAPLE-DW, LIFT, etc.)
5. Ultra-short pulse laser processing
6. VUV laser processing
7. Surface treatment (Texturing, cleaning, annealing, modification, etc.)
8. Micro-patterning and micro-structuring
9. Micro-machining
10. 3-D micro- and nano-fabrication
11. Drilling and cutting
12. Welding and bonding
13. Micro-forming
14. Wafer dicing
15. Marking and trimming
16. Packaging and mounting process
17. Lithography (including EUV source and application)
18. Manufacture of micro devices and systems
19. Film deposition and synthesis of advanced materials (PLD, CVD, etc.)
20. Nano- and micro-particles
21. Medical and biological applications
22. Optics and systems for laser microprocessing
23. Laser devices
24. Industrial applications
25. Photochemistry
26. Free electron laser material processing
27. High-power single-mode fiber lasers
28. Glass/Ceramic processing
29. Others

ABSTRACT DUE DATE: DECEMBER 1, 2009

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